

(1.27 mm) .050"

CLP SERIES

W-PROFILE DUAL WIPE SOCKET

PER ROW

CLP-107-02-F-D-P

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?CLP

Insulator Material:

Black Liquid Crystal Polymer Contact Material: Phosphor Bronze

Plating: Sn or Au over 50 μ" (1.27 μm) Ni

Current Rating (CLP/FTSH): 3.4 A per pin

(2 pins powered)

Voltage Rating: 280 VAC/395 VDC Operating Temp Range: -55 °C to +125 °C

Insertion Depth:

Top Entry = (1.40 mm) .055" minimum, Bottom Entry = (2.41 mm) .095" minimum plus board thickness
DH Entry = (2.31 mm) .091"
to (2.67 mm) .105"
Normal Force:

60 grams (0.59 N) average

Max Cycles: 100 with 10 µ" (0.25 µm) Au RoHS Compliant:

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (02-35) (0.15 mm) .006" max (36-50)* (.004" stencil solution may be available; contact IPG@samtec.com)

RECOGNITIONS

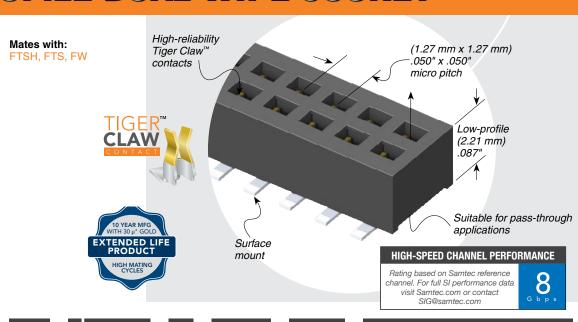
For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- Single row
- · Other platings

Some sizes, styles and options are non-standard, non-returnable.

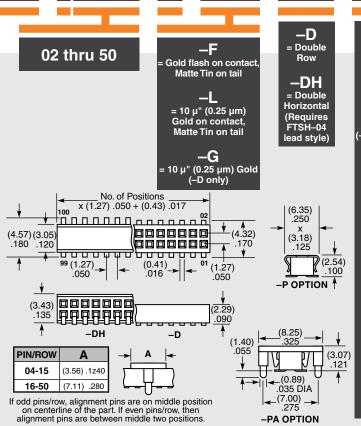


ROW

OPTION

PLATING

OPTION



OTHER OPTION

-BE = Bottom Entry

(Required for bottom entry applications)

= Alignment Pin (Not available with –PA option) (05, 06, 07, 08, 10, 12, 15, 20, 25, 30, 40 positions only) (-DH option and other sizes. Contact Samtec.)

= (4.00 mm) .157" DIA Polyimide film Pick & Place Pad (5 positions minimum)

= Pick & Place Pad (5 positions min. –D only) (Not always necessary for auto placement. See Flex Processing.)

-PA

= Pick & Place Pad with Alignment Pin (-D only) (Not available with -A option)

> -TR = Tape & Reel

= Full Reel Tape & Reel (must order maximum quantity per reel; contact Samtec for quantity breaks)

Due to technical progress, all designs, specifications and components are subject to change without notice WWW.SAMTEC.COM

-PA OPTION